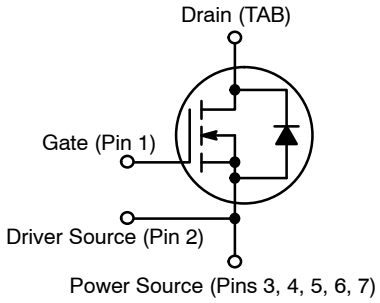
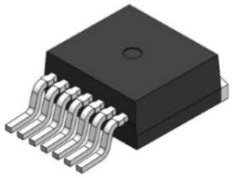
Silicon Carbide (SiC) MOSFET – EliteSiC, 22 mohm, 1200 V, M3S, D²PAK-7L

NTBG022N120M3S

$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D MAX
1200 V	30 mΩ @ 18 V	100 A



N−CHANNEL MOSFET



D²PAK−7L
CASE 418BJ

Features

- Typ. $R_{DS(on)}$ = 22 mΩ @ V_{GS} = 18 V
- Ultra Low Gate Charge ($Q_{G(tot)}$ = 142 nC)
- High Speed Switching with Low Capacitance (C_{oss} = 146 pF)
- 100% Avalanche Tested
- These Devices are RoHS Compliant

Typical Applications

- Solar Inverters
- Electric Vehicle Charging Stations
- Uninterruptible Power Supplies (UPS)
- Energy Storage Systems
- Switch Mode Power Supplies (SMPS)

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	1200	V
Gate−to−Source Voltage			V_{GS}	−10/+22	V
Recommended Operation Values of Gate−to−Source Voltage		T_C<175°C	V_{GSop}	−3/+18	V
Continuous Drain Current (Notes 2, 3)	Steady State	T_C=25°C	I_D	100	A
Power Dissipation (Note 2)	Steady State	T_C=25°C	P_D	441	W
Continuous Drain Current (Notes 2, 3)	Steady State	T_C=100°C	I_D	71	A
Power Dissipation (Note 2)	Steady State	T_C=100°C	P_D	220	W
Pulsed Drain Current (Note 4)	T_C = 25°C		I_{DM}	297	A
Operating Junction and Storage Temperature Range			T_J, T_{stg}	−55 to +175	°C
Source Current (Body Diode) T_C = 25°C, V_{GS} = −3 V (Note 2)			I_S	89	A
Single Pulse Drain−to−Source Avalanche Energy ($I_{L(pk)}$ = 23.1 A, L = 1 mH) (Note 5)			E_{AS}	267	mJ
Maximum Temperature for Soldering (10 s)			T_L	270	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on a FR−4 board using 1 in^2 pad of 2 oz copper.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. The maximum current rating is based on typical $R_{DS(on)}$ performance.
4. Repetitive rating, limited by max junction temperature.
5. E_{AS} of 264 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 23.1 A, V_{DD} = 100 V, V_{GS} = 18 V.

MARKING DIAGRAM



BG022N120M3S = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTBG022N120M3S	D²PAK−7L	800 / Tape & Reel

© Semiconductor Components Industries, LLC, 2021

THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Junction−to−Case − Steady State (Note 2)	$R_{\theta JC}$	0.34	°C/W
Junction−to−Ambient − Steady State (Notes 1, 2)	$R_{\theta JA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
OFF−STATE CHARACTERISTICS						
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 1 mA	1200	−	−	V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	I_D = 1 mA, referenced to 25°C (Note 7)	−	0.3	−	V/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 1200 V, T_J = 25°C	−	−	100	μA
Gate−to−Source Leakage Current	I_{GSS}	V_{GS} = +22/−10 V, V_{DS} = 0 V	−	−	±1	μA
ON−STATE CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 20 mA	2.04	2.72	4.4	V
Recommended Gate Voltage	V_{GOP}		−3	−	+18	V
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = 18 V, I_D = 40 A, T_J = 25°C	−	22	30	mΩ
		V_{GS} = 18 V, I_D = 40 A, T_J = 175°C (Note 7)	−	44	−	
Forward Transconductance	g_{FS}	V_{DS} = 10 V, I_D = 40 A (Note 7)	−	34	−	S
CHARGES, CAPACITANCES & GATE RESISTANCE						
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 800 V (Note 7)	−	3175	−	pF
Output Capacitance	C_{OSS}		−	146	−	
Reverse Transfer Capacitance	C_{RSS}		−	14	−	
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = −3/18 V, V_{DS} = 800 V, I_D = 40 A, (Note 7)	−	142	−	nC
Threshold Gate Charge	$Q_{G(TH)}$		−	11	−	
Gate−to−Source Charge	Q_{GS}		−	16	−	
Gate−to−Drain Charge	Q_{GD}		−	38	−	
Gate−Resistance	R_G	f = 1 MHz	−	1.5	−	Ω
SWITCHING CHARACTERISTICS						
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = −3/18 V, V_{DS} = 800 V, I_D = 40 A, R_G = 4.5 Ω inductive load (Notes 6, 7)	−	18	−	ns
Rise Time	t_r		−	24	−	
Turn−Off Delay Time	$t_{d(OFF)}$		−	47	−	
Fall Time	t_f		−	14	−	
Turn−On Switching Loss	E_{ON}		−	485	−	μJ
Turn−Off Switching Loss	E_{OFF}		−	220	−	
Total Switching Loss	E_{tot}		−	705	−	
SOURCE−DRAIN DIODE CHARACTERISTICS						
Continuous Source−Drain Diode Forward Current (Note 2)	I_{SD}	V_{GS} = −3 V, T_C = 25°C (Note 7)	−	−	89	A
Pulsed Source−Drain Diode Forward Current (Note 4)	I_{SDM}		−	−	297	
Forward Diode Voltage	V_{SD}	V_{GS} = −3 V, I_{SD} = 40 A, T_J = 25°C	−	4.5	−	V

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SOURCE−DRAIN DIODE CHARACTERISTICS						
Reverse Recovery Time	t_{RR}	V_{GS} = −3/18 V, I_{SD} = 40 A, dI_S/dt = 1000 A/μs, V_{DS} = 800 V (Note 7)	–	23	–	ns
Reverse Recovery Charge	Q_{RR}		–	146	–	nC
Reverse Recovery Energy	E_{REC}		–	5	–	μJ
Peak Reverse Recovery Current	I_{RRM}		–	13	–	A
Charge time	t_A		–	13	–	ns
Discharge time	t_B		–	10	–	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. E_{ON}/E_{OFF} result is with body diode
7. Defined by design, not subject to production test.

Typical Characteristics

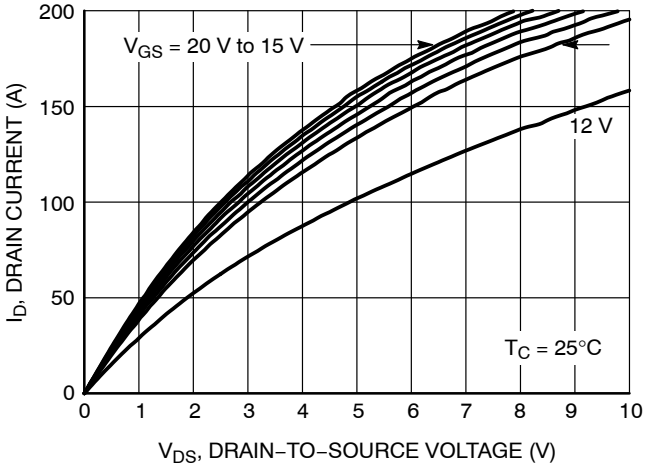


Figure 1. On−Region Characteristics

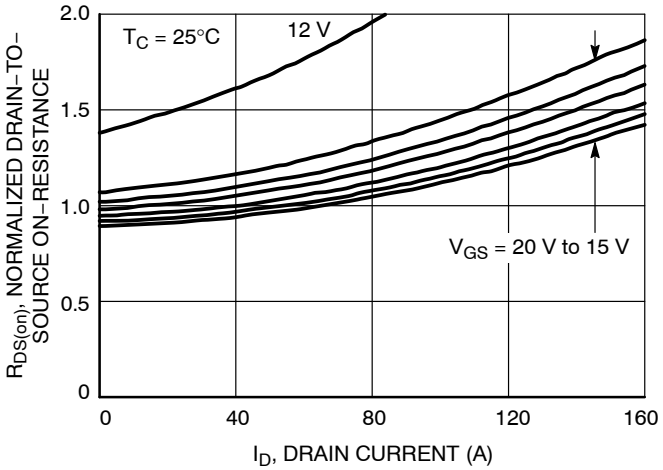


Figure 2. Normalized On−Resistance vs. Drain Current and Gate Voltage

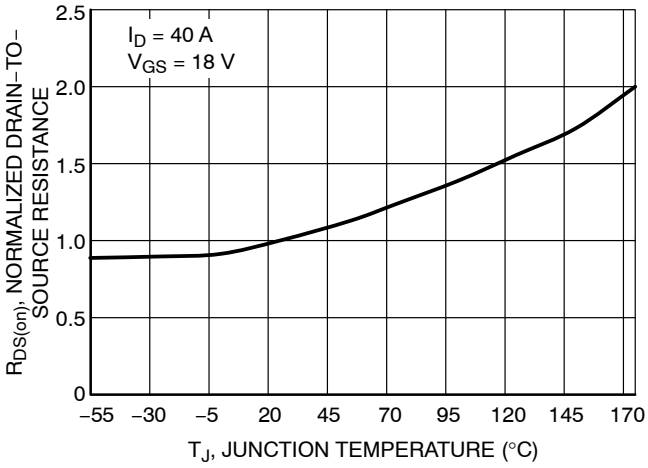


Figure 3. On−Resistance Variation with Temperature

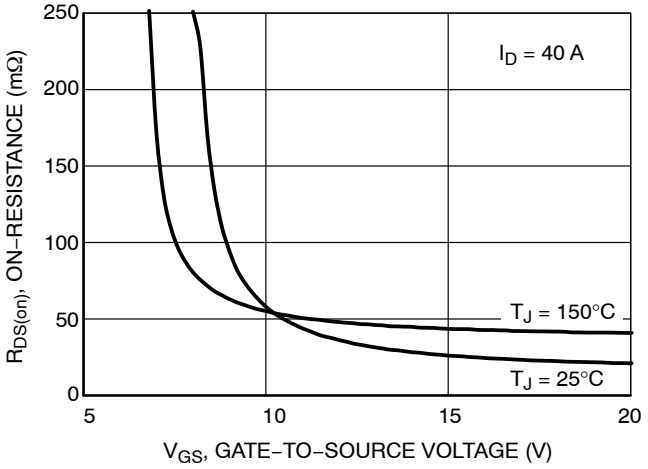


Figure 4. On−Resistance vs. Gate−to−Source Voltage

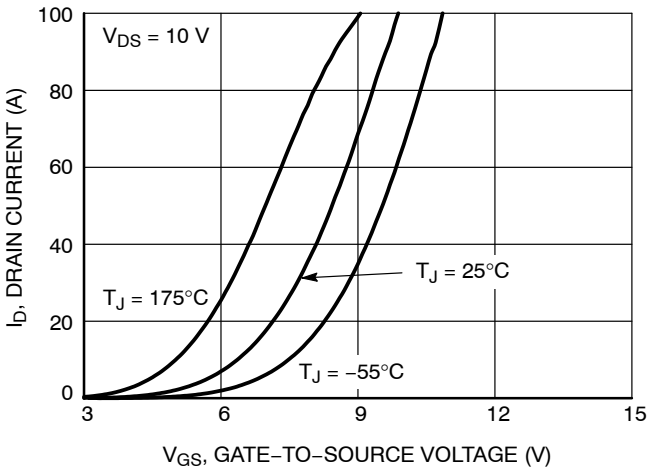


Figure 5. Transfer Characteristics

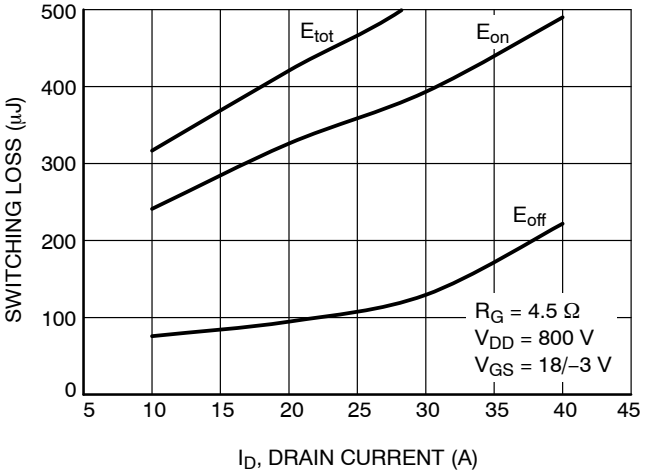


Figure 6. Switching Loss vs. Drain Current

Typical Characteristics

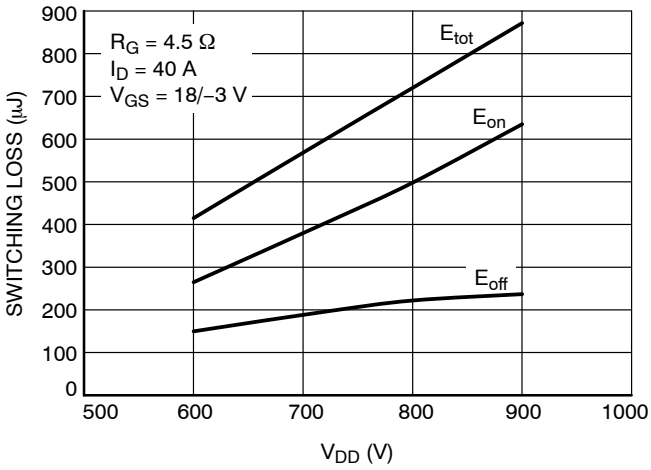


Figure 7. Switching Loss vs. Drain Voltage

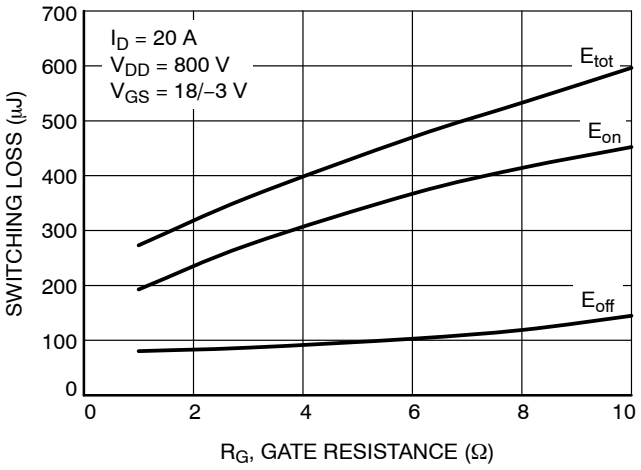


Figure 8. Switching Loss vs. Gate Resistance

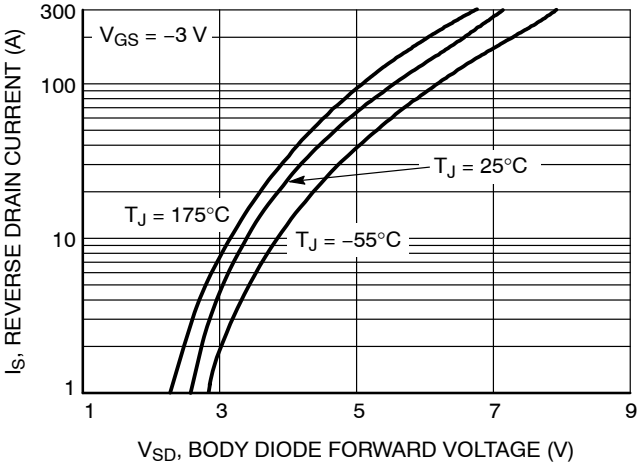


Figure 9. Diode Forward Voltage vs. Current

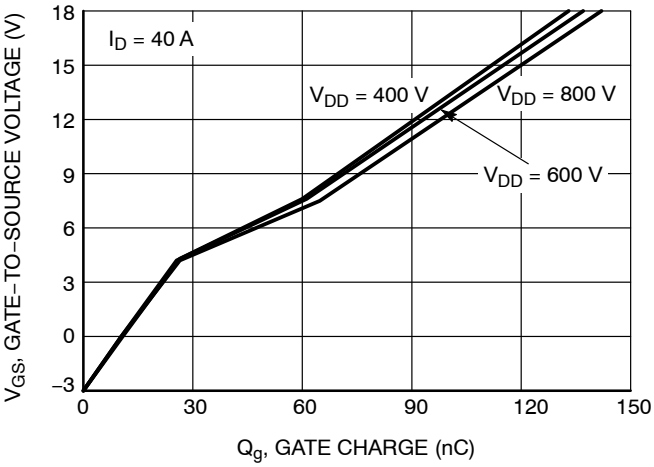


Figure 10. Gate−to−Source Voltage vs. Total Charge

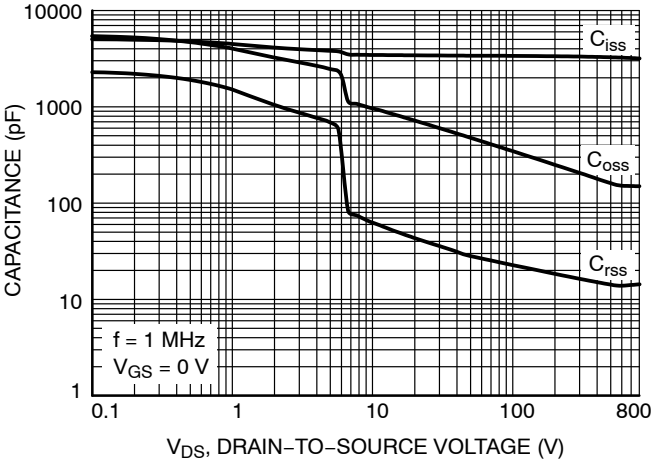


Figure 11. Capacitance vs. Drain−to−Source Voltage

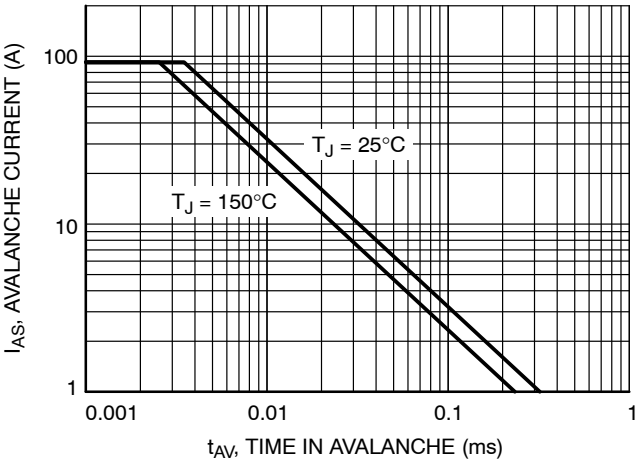


Figure 12. Unclamped Inductive Switching Capability

Typical Characteristics

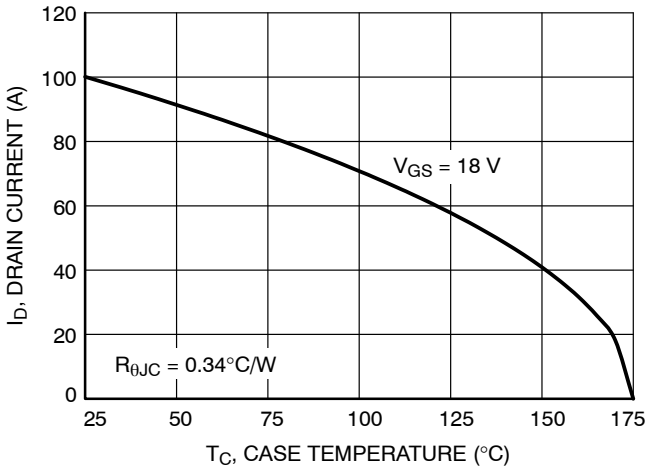


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

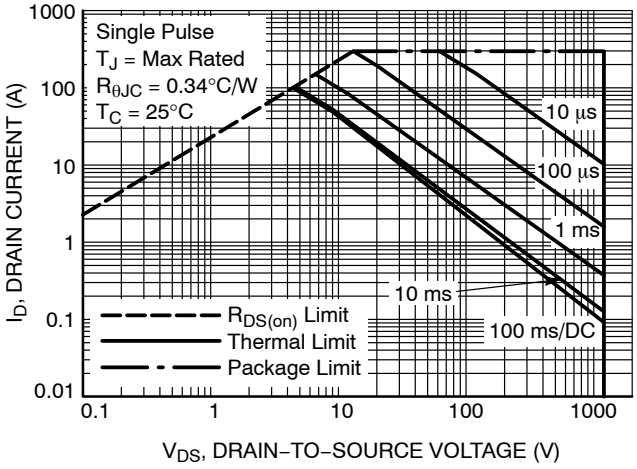


Figure 14. Safe Operating Area

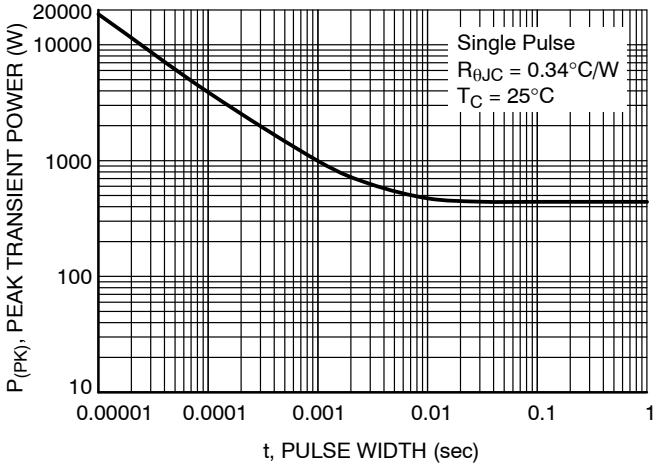


Figure 15. Single Pulse Maximum Power Dissipation

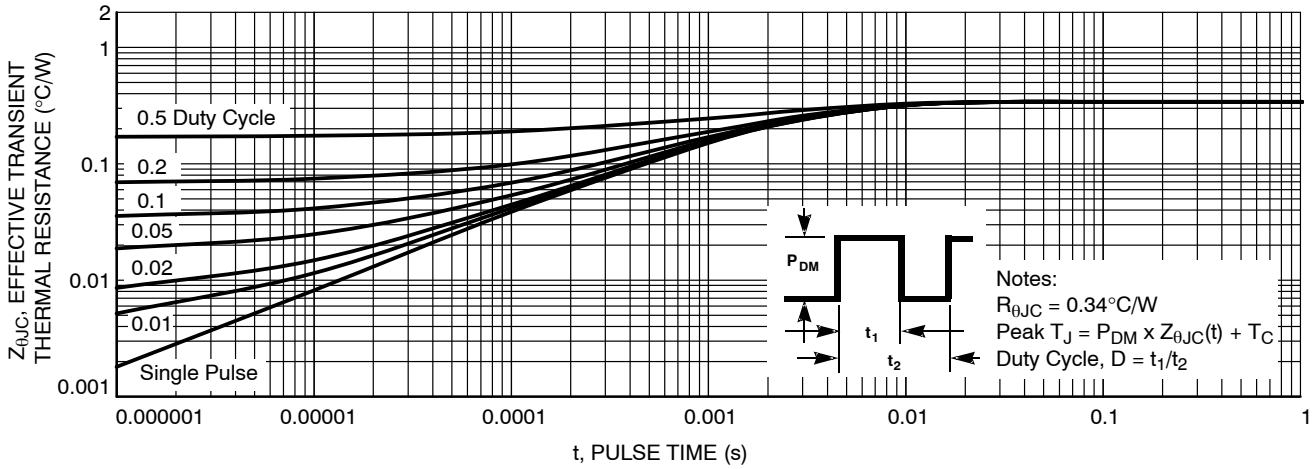
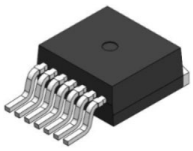


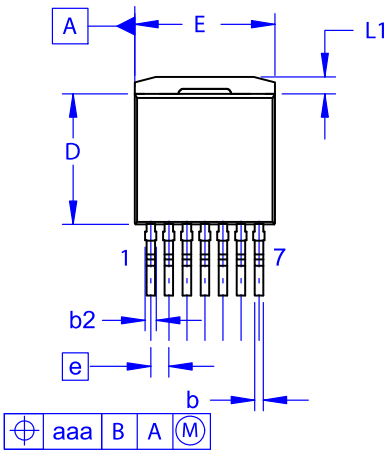
Figure 16. Junction−to−Case Transient Thermal Response

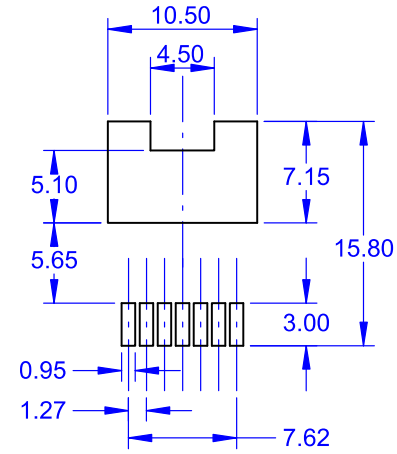
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

D²PAK7 (TO−263−7L HV)
CASE 418BJ
ISSUE B

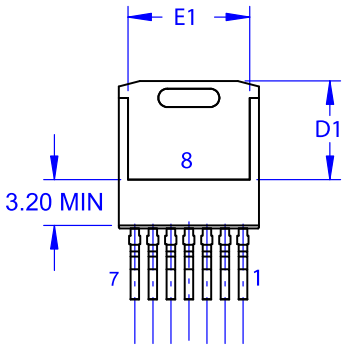
DATE 16 AUG 2019

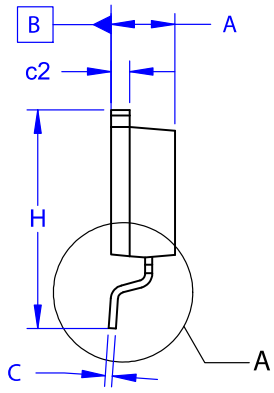






LAND PATTERN RECOMMENDATION





NOTES:

A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. OUT OF JEDEC STANDARD VALUE.
D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

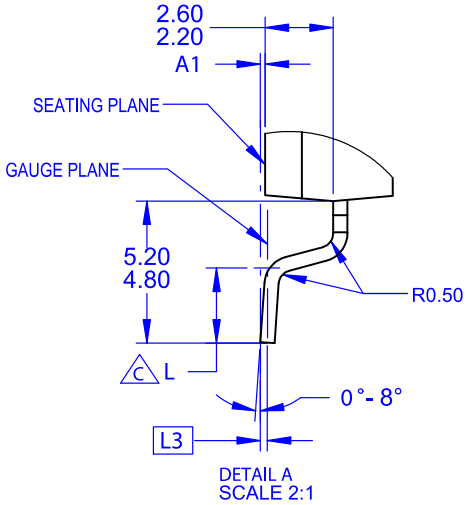
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
c	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
E	9.70	9.90	10.20
E1	7.15	7.65	8.15
e	~	1.27	~
H	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



DETAIL A
SCALE 2:1

DOCUMENT NUMBER:	**98AON84234G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**D²PAK7 (TO−263−7L HV)**	**PAGE 1 OF 1**

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

© Semiconductor Components Industries, LLC, 2018

onsemi, , and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent−Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as−is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales